

SPECIFICATION

T3224C01VR03 – REV. A (320 x 240 RGB TFT 2.2")

CUSTOMER APPROVAL

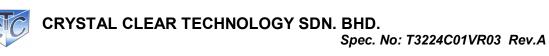
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If the approved document is not returned, CCT will assume it has been approved if any Mass Production Order is issued subsequently.

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LCD Module Specification

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2.0 Record of revision

Re	ev	Date	Item	Page	Comment
A	1	24/01/08			Initial Release





3.0 General specification

Display format	: 240 (W) x RGB x 320 (H) dots
Screen size	: 2.2 inch
Surface treatment	: Anti-glare
Active area	: 33.48mm x 44.64mm
General dimensions	s : 39.40mm x 54.85mm x 2.95mm
Pixel pitch	: 0.1395mm x 0.1395mm
Controller	: Solomon SSD1289
LCD type	: CSTN TFT OLED
Polarizer mode	: Reflective Transflective
	Transmissive
View angle	: 6 O' clock 12 O'clock
	9 O'clock 3 O'clock
Backlight	: NONE LED CCFL
Backlight color	: Yellow Green Amber White
	Blue Green Others
Temperature range	
	Operating 0 to 50 C Operating -10 to 60 C
	Storage -20 to 70 C Storage -20 to 70 C



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Spec. No: T3224C01VR03 Rev.A

4.0 Absolute maximum rating (Ta = 25°C)

Parameter	Symbol	Min.	Max.	Unit	Note
Power supply voltage (VCC,IOVCC)	VCC,IOVCC	-0.3	+4.6	V	1,2
Power supply voltage (VCI ~ VSSA)	VCI ~ VSSA	-0.3	+4.6	V	1,2
Power supply voltage (VLCD ~ VSSA)	VLCD ~ VSSA	-0.3	+6.0	V	3
Power supply voltage (VSSA ~ VCL)	$VSSA \sim VCL$	-0.3	+4.6	V	4
Power supply voltage (VLCD ~ VCL)	$VLCD \sim VCL$	-0.3	+9	V	5
Power supply voltage (VGH ~ VSSA)	VGH ~ VSSA	-0.3	+18.5	V	6
Power supply voltage (VSSA ~ VGL)	$VSSA \sim VGL$	-0.3	+18.5	V	7
Input voltage	Vi	-0.3	VCC+0.3	V	-

Notes:

- 1. VCC, VSSD must be maintained
- 2. To make sure IOVCC \geq VSSD.
- 3. To make sure $VCI \ge VSSA$.
- 4. To make sure $VLCD \ge VSSA$.
- 5. To make sure VLCD \geq VCL.
- 6. To make sure VGH \geq VSSA.
- 7. To make sure $VSSA \ge VGL$.
- 8. The modules may be destroyed if they are used beyond the absolute maximum ratings.



5.0 Electrical characteristics ($Ta = 25^{\circ}C$)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply voltage (logic)	VCC-GND		2.2	2.8	3.3	V
Supply voltage (for analog power supply)	VCI		2.5	2.8	3.3	V
TFT gate ON voltage	VGH (Note 2)		-	15	-	V
TFT gate OFF voltage	VGL (Note 3)	At Ta=25°C±5°C (Note 4)	-	-10	-	V
TFT common electrode	VcomH		2.5	ı	4	V
voltage	VcomL		-1.5	ı	0	V
Input signal voltage	$ m V_{IH}$	"H" level	0.8xIOVCC	ı	IOVCC	V
input signal voltage	$ m V_{IL}$	" L" level	-0.3	ı	0.2xIOVCC	V
Supply current (Logic & LCD)	ICC	VCC=2.8V	-	-	18.0	mA
Supply voltage of white LED backlight	VLED =V _{AK}	Forward current =15mA	-	13.2	-	V
Luminance (on the backlight surface)		Number of LED dies = 4	3000	3300	-	cd/m ²
Luminance of white LED backlight (through TFT panel)		Forward current =15mA, backlight on, panel no display, measure=~30cm	200	-	-	cd/m ²

Note (1): There is tolerance in optimum LCD driving voltage during production and it will be within the specified range.

Note (2): VGH is TFT Gate operating voltage.

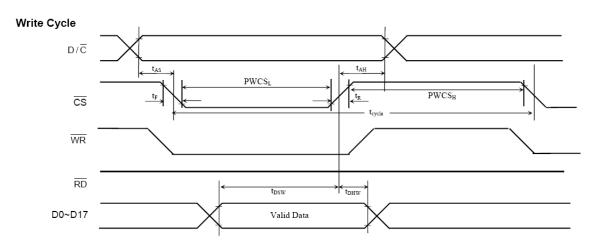
Note (3): VGL is TFT Gate operating voltage. The low voltage level VGL signal must be fluctuates with same phase as Vcom in case of Cadd (Storage on Gate) structure.

Note (4): Vcom must be adjusted to optimize display quality.

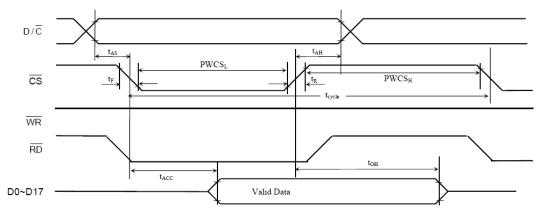


5.1 Driver IC AC Characteristics

5.1.1 8080-Series MPU Parallel Interface Characteristics



Read Cycle

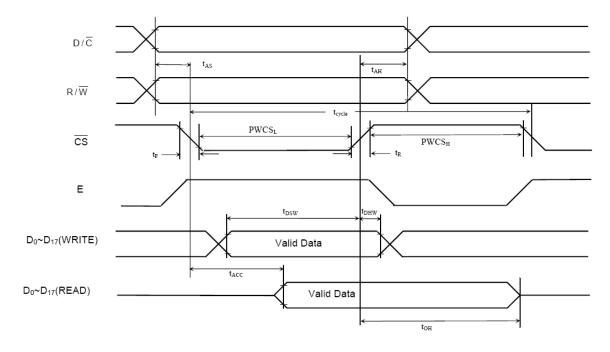


Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time (write cycle)	100	-	-	ns
t _{cycle}	Clock Cycle Time (read cycle)	1000	-	-	ns
t _{AS}	Address Setup Time	0	-	-	ns
t _{AH}	Address Hold Time	0	-	-	ns
t _{DSW}	Data Setup Time	5	-	-	ns
t _{DHW}	Data Hold Time	5	-	-	ns
t _{ACC}	Data Access Time	250	-	-	ns
t _{OH}	Output Hold time	100	-	-	ns
PWCS _L	Pulse Width /CS low (write cycle)	50	-	-	ns
PWCS _H	Pulse Width /CS high (write cycle)	50	-	-	ns
PWCS _L	Pulse Width /CS low (read cycle)	500	-	-	ns
PWCS _H	Pulse Width /CS high (read cycle)	500	-	-	ns
t _R	Rise time	-	-	4	ns
t _F	Fall time	-	-	4	ns



5.1.2 6800-Series MPU Parallel Interface Characteristics

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time (write cycle)	100	-	-	ns
t _{cycle}	Clock Cycle Time (read cycle)	1000	-	-	ns
t _{AS}	Address Setup Time	0	-	-	ns
t _{AH}	Address Hold Time	0	-	-	ns
t _{DSW}	Data Setup Time	5	-	-	ns
t _{DHW}	Data Hold Time	5	-	-	ns
t _{ACC}	Data Access Time	250	-	-	ns
toH	Output Hold time	100	-	-	ns
PWCS _L	Pulse width /CS low (write cycle)	50	-	-	ns
PWCS _H	Pulse width /CS high (write cycle)	50	-	-	ns
PWCS _L	Pulse width /CS low (read cycle)	500	-	-	ns
PWCS _H	Pulse width /CS high (read cycle)	500	-	-	ns
t _R	Rise time	-	-	4	ns
t _F	Fall time	-	-	4	ns





6.0 Environmental requirements

Item	Operating temperature (Topr)		Storage temperature (Tstg) (Note 1)		Remark
	Min.	Max.	Min.	Max.	
Ambient temperature (Ta)	-10°C	+60°C	-20°C	+70°C	Dry
Humidity (Note 1)	90% max. RH for Ta ≤ 40°C < 50% RH for 40°C < Ta ≤ Maximum operating temperature				No condensation
Vibration (IEC 68-2-6) cells must be mounted on a suitable connector	Frequency: 10 Amplitude: 0. Duration: 20	3 directions			
Shock (IEC 68-2-27) Half-sine pulse shape	Pulse duration: 11 ms Peak acceleration: 981 m/s ² = 100g Number of shocks: 3 shocks in 3 mutually perpendicular axes. 3 directions				

Note: The product cannot sustain at extreme storage conditions for long time.



7.0 LCD specification

7.1 Electro-optical characteristic

Item		Cumbal	Conditions	Spe	cificatio	ns	Unit	Note
		Symbol	Conditions	Min.	Тур.	Max.	Unit	Note
Transmittance	Э	T%			6.9		%	All left side
Contrast Ratio	0	CR		150	200	NA	-	data are based
Response Tin	20	T _R		NA	10	25	ms	on following
Response III	ile	T _F		NA	20	40	ms	condition –
	Red	X _R		0.615	0.645	0.645	-	NTSC: 50%
	Red	YR	Viewing normal angle $\theta_X = \theta_Y$	0.343	0.373	0.373	-	LC: 5066
	Green	X_G		0.307	0.337	0.337	-	Light: C light
Chromoticity		Y _G	=0°	0.563	0.593	0.593	-	(Machine:
Chromaticity	Blue	X _B		0.133	0.163	0.163	-	BM5A)
		Y _B		0.150	0.180	0.180	-	Normal
	Mhito	Xw		0.309	0.339	0.339	1-	Polarizer
	White	Yw		0.350	0.380	0.380	-	Reference
	1100	θ_{X+}		_	45			Only
Viewing	Hor.	θ _{X-}	Center	-	45	-	deg.	
Angle	.,	θ_{Y+}	CR≥10	-	35	-		
	Ver.	θ _Y .		-	15	-		

*Note (1) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

Contrast Ratio (CR) = L63 / L0

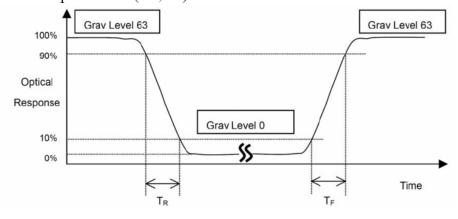
L63: Luminance of gray level 63

L0: Luminance of gray level 0

CR = CR (10)

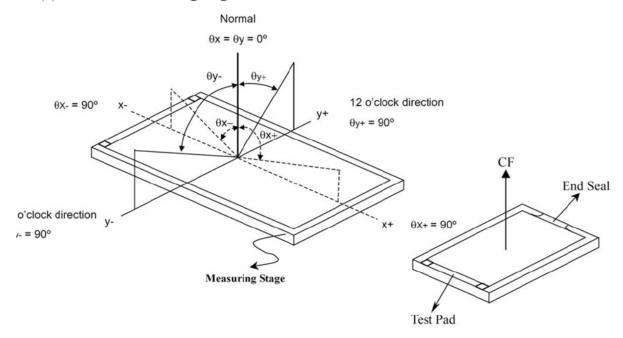
CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (6).

*Note (2) Definition of Response Time (TR, TF):





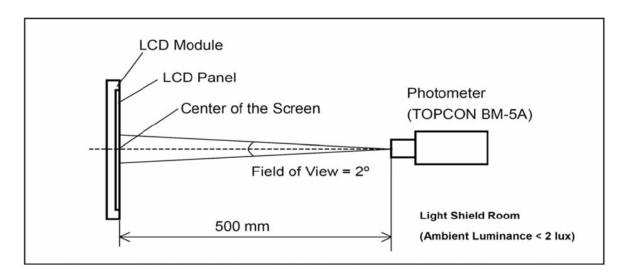
*Note (3) Definition of Viewing Angle



*** The above "Viewing Angle" is the measuring position with Largest Contrast Ratio; not for good image quality. View Direction for good image quality is 6 O'clock. Module maker can increase the "Viewing Angle" by applying Wide View Film.

*Note (4) Measurement Set-Up

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.





8.0 Interface

Pin no.	Symbol	Description
1	VCC	Power supply for internal logic
2	VCI	Power supply for step-up circuit
3	GND	Ground terminal
5	GND	Ground terminal
5	/CS	Chip select signal (Active low)
6	RS	Command/Data select
7	/WR (R/W)	Write signal (Active low)
8	/RD (E)	Read signal (Active low)
9	DB0	
10	DB1	
11	DB2	
12	DB3	
13	DB4	
14	DB5	
15	DB6	
16	DB7	
17	DB8	Data bus
18	DB9	Data ous
19	DB10	
20	DB11	
21	DB12	
22	DB13	
23	DB14	
24	DB15	
25	DB16	
26	DB17	
27	/RESET	Reset signal (Active low)
28	PS0	Selection pin
29	PS1	Selection pin
30	PS2	Selection pin
31	K	Cathode of backlight
32	A	Anode of backlight

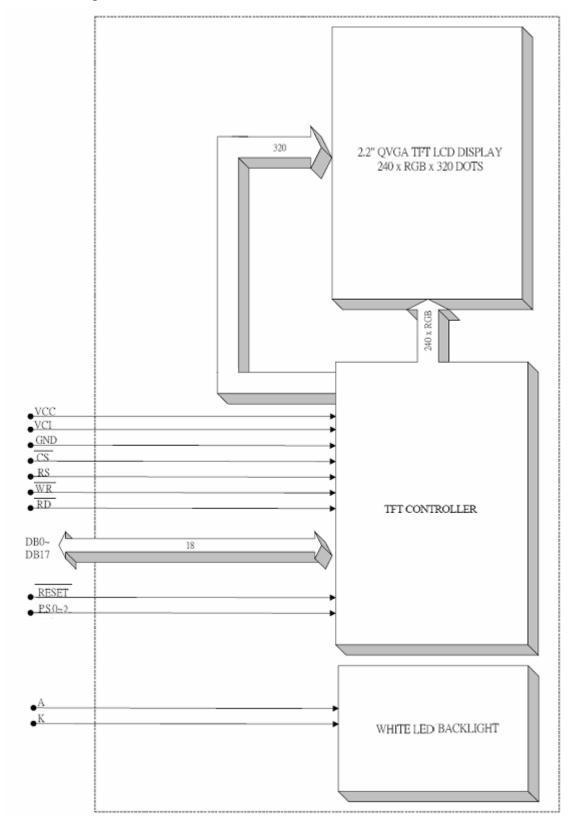
PS2	PS1	PS0	Interface mode
0	1	1	16-bits 6800 parallel interface
0	1	0	8-bits 6800 parallel interface
0	0	1	16-bits 8080 parallel interface
0	0	0	8-bits 8080 parallel interface

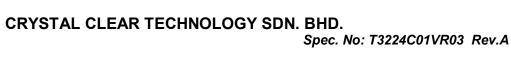
PS3 is set to be high internally on the FPC.

To set PS3 low, please remove R9 and add jumper to R10 on FPC.



9.0. Block Diagram





10.0 TFT Panel inspection

				· Santino	Acceptable counts	
1. Dot Defects	$\qquad \qquad \updownarrow$	Classifications		Visible area	Non-visible area	
	<mark>← a</mark> > b	A sunda		Ф≦0.10	Don't care	
		A grade		0.10<Φ≦0.15	1	
	Φ=(a+b)/2	Danada		0.15<Φ≦0.2	3 Don't care	Don't care
		B grade		0.1<Φ≦0.15	5	
2. Line Defects	L	Classificat		•••	Acceptable counts	
				ions	Visible area	Non-visible area
		A grade	W	≦0.03,L≦3.0	Don't care	
			0.03<	W≦0.05,L≦2.0	1	Don't care
		B grade		W ≤ 0.05,L ≤ 3.0	3	
3.Glass bur	Heat press Head O. 3max Top glass C Bottom Glass O. 2min			1). b \leq 1.0, and not affect outline dimension and assemble 2). Around bonding area, b must fulfill b \leq (c-0.2) max		
	0.8max	9.0max	,			n and assemble
4. End seal dimension	v seal	Pane		1). Depth =< 0. area 2). Height =< 0. 3). Length =< 9	8 mm	enter to the visible
5. Glass edges breakage	Conductive Pad IC Area Top Glass Bottom Glass Broken Area		Categories			
			A If a ≦ tar	$a \leqq t \text{ and } b \leqq 1.0, c \text{ has no limit}$		
			В	a ≦ t, 1≦b≦1.5, c≦3		
				Co.	$b \le 0.5$, and th	and /or alignment e FPC contacts
	Breakage on step glass	S		D Side break mark.	age should not	damage alignment



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Frame C b a t Inside of frame Outside of frame	b should not arrive inside of frame	
Breakage between upper and lower glass Frame t Inside of frame Outside of frame	b should not arrive outside of frame	
Corner breakage	$a \le t$, $b \le 2.0$, $c \le 3.0$	
a t	Corner breakage should not damage track and /or alignment mark.	

<u>Items</u>	Position	Inspection Criteria
6.Crack	Whole area	Not allowed
7.Surface cleanness	Step surface	The impurity which is easy to clean is allowed, glass particle is not allowed.

Remark: a: breakage thickness; b: breakage depth; c: breakage length; t: glass thickness; h: damaged FPC contact length; L: total length of FPC contacts (Unit: mm)



11.0 Mechanical specification 13,0±0,5 (17.7 ± 0.5) 3,0 0.35 TYP. 16.5±0.07 0.5±0.07 P0.5x(32-1)=15.5±0.05 KAPTON TAPE--BLACK TAPE COMPONENT AREA(H:1,1MAX)_ CONTACT SIDE -BACKLIGHT DP190 SECTION XX 0.3 ± 0.05 FR4 0.23 MAX 1,0±88,48 21,65±0,5 GLASS=52.816±0.2 5,0±46,84 (S,S) 8.5±0.2 (43.44-A.A) (3.092)

